

## EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	107	nitric acid with "80" degrees	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2006/06/25 15:12
S2	17	nitric acid with "80" degrees and semiconductor	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2006/06/25 15:12
S3	305	heated with nitric acid and semiconductor	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2006/06/25 15:12
S4	0	heated with nitric acid with defect with removal and semiconductor	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2006/03/30 00:53
S5	1	heated with nitric acid with defect and semiconductor	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2006/03/30 00:55
S6	305	heated with nitric acid and semiconductor	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2006/03/30 00:55
S7	31	heated with nitric acid with oxide and semiconductor	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2006/03/30 00:57
S8	13	heated with nitric acid with known and semiconductor	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2006/03/30 01:00
S9	22	heat\$3 with nitric acid with known and semiconductor	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2006/03/30 10:02

S10	0	heat\$3 with nitric acid with known withoxide	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2006/03/30 10:03
S11	25	heat\$3 with nitric acid with known with oxide	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2006/03/30 10:03
S12	0	nitric acid with "80" degrees with known	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2006/03/30 10:07
S13	34	nitric acid with degrees with known	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2006/06/25 15:14
S14	6	nitric acid with degrees with known and silicon	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2006/03/30 10:15
S15	0	heated near nitric acid with known and silicon	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2006/03/30 10:16
S16	33	heated near nitric acid and silicon	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2006/03/30 10:35
S17	198	"hno.sub.3" and "80" degrees	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2006/06/25 15:12
S18	13	"hno.sub.3" with "80" degrees	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2006/03/30 10:36
S19	2	("6117689").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/03/31 14:28

S20	5	("2005013689").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/03/31 14:29
S21	2	("20050013689").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/03/31 14:30
S22	1	("20050136689").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/03/31 14:30
S23	206	"hno.sub.3" and "80" degrees	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2006/06/25 15:12
S24	107	nitric acid with "80" degrees	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2006/06/25 15:12
S25	17	nitric acid with "80" degrees and semiconductor	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2006/06/25 15:12
S26	310	heated with nitric acid and semiconductor	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2007/08/06 07:24
S27	3923	(438/694).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/08/06 07:24
S28	414	(438/695).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/08/06 07:25
S29	1314	(438/745).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/08/06 07:25

S30	371	(438/775).CCL.S.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/08/06 07:25
S31	120	(438/776).CCL.S.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/08/06 07:25
S32	1033	(438/770).CCL.S.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/08/06 07:25
S33	34	nitric acid with degrees with known	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2006/06/25 15:14
S34	278	NAKAMURA-MANABU.in.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2007/08/06 07:25
S35	13	NANSEI-HIROUYUKI.in.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2007/08/06 07:26
S36	12	SERA-KENTARO.in.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2007/08/06 07:26
S37	25	HIGASHI-MASAHICO.in.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2007/08/06 07:26
S38	10	UTSUNO-YUKIHIRO.in.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2006/06/25 15:16
S39	185	TAKAGI-HIDEO.in.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2007/08/06 07:26

S40	63	KAJITA-TATSUYA .in.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2007/08/06 07:26
S41	74	(257/e21.221).CQLS	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/06/25 15:21
S42	4	tunnel oxide with plasma oxidation	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2007/02/07 12:27
S43	3	nitric acid and tunnel oxide and plasma with oxidation	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2007/02/07 12:29
S44	335	nitric acid with clean\$3 same semiconductor	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2007/02/07 12:30
S45	1	nitric acid with clean\$3 same semiconductor and tunnel oxide	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2007/02/07 12:31
S46	108	nitric acid with clean\$3 same semiconductor same oxide	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2007/02/07 12:33
S47	7	nitric acid with clean\$3 same semiconductor same oxide and plasma with oxid\$6	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2007/08/06 07:27
S48	16	"5423944"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2007/02/07 12:42
S49	518	acid with ozone and plasma with oxidation	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2007/02/26 13:14

S50	18	acid with ozone and plasma with oxidation and insulation film	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2007/02/26 18:24
S51	2	("5423944").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/02/26 18:29
S52	117	nitric acid with ozone same silicon	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2007/02/26 18:30
S53	25	nitric acid with ozone same silicon same temperature	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2007/02/26 18:31
S54	2	("5412216").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/02/26 20:05
S55	2	("5412246").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/02/26 20:05
S56	2	("5423944").PN.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/08/06 06:55
S57	2	("5412246").PN.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/08/06 06:54
S58	4054	(438/694).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/08/06 07:24
S59	347	heated with nitric acid and semiconductor	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2007/08/06 07:25

S60	455	(438/695).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/08/06 07:25
S61	1535	(438/745).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/08/06 07:25
S62	428	(438/775).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/08/06 07:25
S63	138	(438/776).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/08/06 07:25
S64	1118	(438/770).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/08/06 07:25
S65	308	NAKAMURA-MANABU.in.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2007/08/06 07:25
S66	20	NANSEI-HIROYUKI.in.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2007/08/06 07:26
S67	14	SERA-KENTARO.in.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2007/08/06 07:26
S68	38	HIGASHI-MASAHIKO.in.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2007/08/06 07:26
S69	192	TAKAGI-HIDEO.in.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2007/08/06 07:26

S70	65	KAJITA-TATSUYA .in.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2007/08/06 07:26
S71	8	nitric acid with clean\$3 same semiconductor same oxide and plasma with oxid\$6	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2007/08/06 07:39
S72	1569	(257/e21.228).CQLS.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/08/06 07:39
S73	193	radial line slot antenna with plasma with microwave	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/02/27 21:18
S74	7	radial line slot antenna with plasma with microwave same insulation film	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/02/27 21:18
S76	68	(radial line slot antenna or rlsa) with plasma same microwave and insulation film	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/02/27 21:25
S77	7	(radial line slot antenna or rlsa) with plasma same microwave same insulation film	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/05/01 17:19
S78	2	("5412246").PN.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/11/23 12:28
S79	0	"5412246" and sonos	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/11/23 12:33



S80	22	"5412246"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/11/23 12:33
S81	37	sonos and low with temperature with plasma with oxid\$6	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/11/23 12:34
S82	7038	sonos	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/11/23 12:40
S83	1	sonos same low with temperature with plasma with oxid\$6	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/11/23 12:40
S84	8	sonos same low with temperature with oxid\$6	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/11/23 12:41
S85	0	sonos same embedded bitline	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/11/23 13:25
S86	131	embedded with bitline	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/11/23 13:25
S87	2	embedded with bitline and sonos	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/11/23 13:25

S88	12	embedded same bitline and sonos	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/11/23 13:26
S89	2	("20040082198").PN.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/11/23 13:29
S90	5	embedded same bit-line and sonos	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/11/23 13:29
S91	1	embedded and S89	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/11/23 13:30
S92	0	embedded bit-line-type and sonos	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/11/23 13:31
S93	0	embedded same bit-line-type and sonos	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/11/23 13:31
S94	2	bit-line-type and sonos	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/11/23 13:31
S95	0	buried same bit-line-type and sonos	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/11/23 13:46

S96	0	burried same bit-line-type and sonos	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/11/23 13:46
S97	0	burried same bit-line and sonos	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/11/23 13:46
S98	5	embed\$4 same bit-line and sonos	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/11/23 13:47
S99	3599	(438/257).CCLS	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/11/23 14:02
S100	1185	(438/770).CCLS	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/11/23 14:03
S101	474	(438/775).CCLS	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/11/23 14:03
S102	147	(438/776).CCLS	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/11/23 14:03
S103	333	NAKAMURA-MANABU.in.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/11/23 14:03
S104	21	UTSUNO-YUKIHIRO.in.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/11/23 14:03

S105	18	SERA-KENTARO.in.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/11/23 14:04
S106	42	HI GASHI-MASAHICO.in.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/11/23 14:04
S107	42	S106	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/11/23 14:04
S108	21	UTSUNO-YUKIHIRO.in.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/11/23 14:04
S109	21	S108	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/11/23 14:04
S110	201	TAKAGI-HIDEO.in.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/11/23 14:04
S111	201	S110	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/11/23 14:04
S112	69	KAJITA-TATSUYA.in.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/11/23 14:04
S113	69	S112	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/11/23 14:04
S114	1598	(257/e21.228).CQLS.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/11/23 14:04

S115	343	NAKAMURA-MANABU.in.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/03/11 23:16
S116	34	NANSEI-HIROYUKI.in.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/03/11 23:16
S117	19	SERA-KENTARO.in.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/03/11 23:16
S118	44	HIGASHI-MASAHICO.in.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/03/11 23:16
S119	21	UTSUNO-YUKIHIRO.in.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/03/11 23:16
S120	203	TAKAGI-HIDEO.in.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/03/11 23:16
S121	69	KAJITA-TATSUYA.in.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/03/11 23:16
S122	628	S115 or S116 or S117 or S118 or S119 or S120 or S121	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/03/11 23:16
S123	1596	(257/e21.228).CQLS.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/03/11 23:16
S124	8	sonos same low with temperature with oxid\$6	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/03/11 23:16

S125	40	sonos and embed\$3 with bit with line	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/03/11 23:17
S126	0	sonos and embed\$3 with bit with line and radial slot line	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/03/11 23:18
S127	9	sonos and embed\$3 with bit with line and radial line slot	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/03/11 23:19
S128	3706	(438/257).CCLS	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/03/11 23:32
S129	1765	(438/745).CCLS	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/03/11 23:32
S130	483	(438/775).CCLS	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/03/11 23:32
S131	1	sonos and embed\$3 with bit with line and radial line slot and acid	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/03/26 15:16
S132	1	sonos and embed\$3 with bit with line and radial line slot and acidic	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/03/26 15:16
S133	343	NAKAMURA-MANABU in.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/03/26 16:23

S134	34	NANSEI-HIROYUKI.in.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/03/26 16:23
S135	19	SERA-KENTARO.in.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/03/26 16:23
S136	44	HIGASHI-MASAHICO.in.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/03/26 16:23
S137	21	UTSUNO-YUKIHIRO.in.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/03/26 16:23
S138	203	TAKAGI-HIDEO.in.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/03/26 16:23
S139	69	KAJITA-TATSUYA.in.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/03/26 16:23
S140	628	S133 or S134 or S135 or S136 or S137 or S138 or S139	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/03/26 16:23
S141	1198	(438/770).CCLS	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/03/26 16:23
S142	485	(438/775).CCLS	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/03/26 16:23
S143	148	(438/776).CCLS	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/03/26 16:23

S144	3715	(438/257).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/03/26 16:24
S145	0	(257/21.288).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/03/26 16:24
S146	140	(257/e21.288).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/03/26 16:24
S147	342	(438/262).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/03/26 16:27
S149	0	S147 and sonos and radial line slot	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/03/26 16:28
S150	26	S147 and sonos	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/03/26 16:28
S151	0	S147 and sonos and acidic	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/03/26 16:28

3/ 26/ 2009 6:18:27 PM

C:\Documents and Settings\bsmith5\My Documents\EAST\Workspaces\ 10659748.wsp